

GLOBAL SEMICONDUCTOR PACKAGING MATERIALS OUTLOOK

2023 EDITION

Global Semiconductor Packaging Materials Outlook (2023 Edition) is a comprehensive market research study that examines semiconductor packaging technology trends and their impact on the packaging materials markets. The report quantifies the packaging materials markets by segment and by region, highlights new opportunities for emerging package form factors, defines supplier market share, and presents market forecasts through 2027.

Global Semiconductor Packaging Materials Outlook is an essential business tool for anyone interested in the plastic packaging materials arena. Packaging materials directly affect the performance, reliability and cost of semiconductors, and advancements in packaging materials technology offer the potential for significant improvement across all these areas.

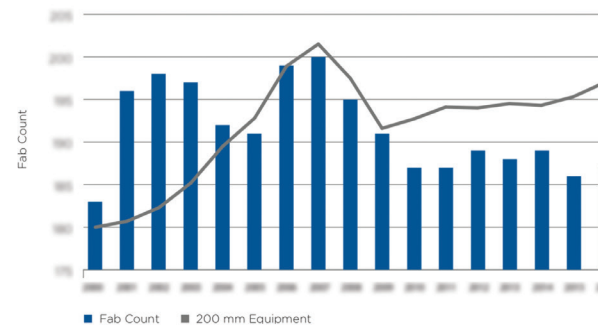


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2—SEMICONDUCTOR PACKAGING AND INDUSTRY TRENDS

FIGURE 2.3 200 MM FAB CAPACITY TRENDS (EXCLUDING LED, EPI, R&DS)



\$3.8 billion to \$3.9 billion annually. The market contracted in 2019 and will decline an estimated -2% in 2020 before growing 9% in 2021. Equipment spending is directed towards

2.3.4 Industry Trends Summary
In summarizing recent industry trends, the report highlights the impact of the COVID-19 pandemic on the semiconductor packaging materials market.

FEATURES

- Technology trends
- Regional market size
- Five-year market forecasts
- Supplier market share
- Market size in revenue and units
- Capacity and utilization trends
- Supply chain Issues

BENEFITS

- Gain insights to worldwide packaging material technology trends, market size, and market forecast
- Understand key package offerings and technologies
- Use benchmark data to validate business opportunities and assumptions

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METHODOLOGY

The source of information for this study are in-person interviews with over 150 material suppliers, packaging subcontractors, and semiconductor manufacturers from around the world. The authors of this report used primary research and modeling to develop market size information, and developed five-year market forecasts based on different scenarios of new technology penetration and market growth.

2023 PRICING INFORMATION — ONE-TIME PURCHASE

	SEMI MEMBER	NON-MEMBER
1 user	\$7,500	\$10,250
2-3 users	\$16,000	\$22,150
4+ users- Corporate License	\$33,250	\$43,750

CONDENSED TABLE OF CONTENTS

1 INTRODUCTION

Methodology
Assumptions
Report Organization

2 SEMICONDUCTOR PACKAGING

Industry Market Trends Regional
and Market Issues Materials
Needs— Customer Input
End-market Applications

3 SUBSTRATES

Laminate Substrates
Build-up Substrates
Organic Substrates
Markets and Forecast
Pricing
Supply

4 LEADFRAMES

Technology Trends Markets and
Forecast Supply

5 BONDING WIRE

Technology Trends Markets and
Forecast Pricing Trends Supply

6 ENCAPSULATION MATERIALS

Technology Trends Markets and
Forecast Supply

7 UNDERFILL MATERIALS

Technology Trends Markets and
Forecast Supply

8 DIE ATTACH MATERIALS

Technology Trends Markets and
Forecast Supply

9 WAFER LEVEL PACKAGE DIELECTRICS

Technology Trends Markets and
Forecast Supply

10 WAFER LEVEL PLATING CHEMICALS

Technology Trends
Markets and Forecast Supply

11 SUMMARY AND CONCLUSIONS

12 APPENDICES



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